Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Plurals Time Stamp	
	704	451/56.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	S.	- FF0	2004/09/22 10:37	
	478	451/60.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	S.	HO.	2004/09/22 10:37	
	254722	polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	No.	- T-0	2004/09/22 10:38	
	2208	451/41.ccls. and polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR.	OFF.	2004/09/22 10:38	
	480	451/56.ccls. and polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	SO.	FF0	2004/09/22 10:38	
	380	451/60.ccls. and polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	So.	H0	2004/09/22 10:39	
	419839	ped	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR.	#0 #	2004/09/22 10:39	
	84	"3-hydroxy-4-pyrones"	US-PGPUB; USPAT; EPO; JPO; DERWENT	NO.	100年	2004/09/22 13:04	
	955901	("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane borohydrides (dialkylamine adj aboranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (sohvated adj electrons) (sulfurous adj acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT	% O	#0	2004/09/22 13:15	

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95.	955901	("3-hydroxy-4-pyrones") or	US-PGPUB;	OR	- 10	2004/09/22 13:17
		(hydroxy adj1 butyrolactones) or borane or borohydrides or (dialkylamine adj boranes) or formaldehyde or (formic adj acid) or hydrogen or hydroquinones or hydrogen or hydroquinones or hydroylamine or (hypophosphorous adj acid) or trihydroxybenzene or (sohated adj electrons) or (suffurous adj acid)	USPAT; EPO; JPO; DERWENT			
0	303143	("428" or "156" or "51").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	FF0	2004/09/22 13:18
4.	43264	(("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane burohydrides (dalkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trilhydroxybenzene (sofwate adj electrons) (sulfurous adj acid)) and (("428" or "156" or "51").clas.)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ĕ	H0	2004/09/22 13:18
	0	"451.clas"	US-PGPUB; USPAT; EPO; JPO; DERWENT	Se .	±00	2004/09/22 13:18
Ó	64433	"451".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR.	0FF	2004/09/22 13:18
	1097	(("3-hydroxy-4-pyrones") or (hydroxy adj! butyrolactones) or borane borohydrides (dalkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (sobxated adj electrons) (suffurous adj acid)) and "451".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	ő	H0	2004/09/22 13:19
<u> </u>	2868440	reducing agent	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	оғғ	2004/09/22 13:23

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2004/09/22 13:23	2004/09/22 13:34	2004/09/22 13:31	2004/09/22 13:31	2004/09/22 13:42
4 0	HO.	- OFF	₩ E	96F
8	క	R	æ	OR
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
((("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane bronybrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (sokvatet adj electrons) (sulfurous adj acid) 1 and "451".clas.) and (reducing agent)	(451/41.ccls. and polish\$3) and pad	(451/56.ccts. and polish\$3) and pad	(451/60.ccls. and polish\$3) and pad	(('3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or boarne bronvhyrides (daikylamine adj boranes) formaldehyde (formic adj acd) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxyhenzene (sobvated adj electrons) (sutfurous adj acid) 1, nithydroxyhenzene (sobvated adj electrons) (sutfurous adj acid) 1 and (((451/41.ccks. and polish\$3) and pad) or ((451/60.ccks. and polish\$3) and pad))
8334	1562	396	263	337
213	818	S19	820	221

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2004/09/22 13:35	2005/01/24 13:20	2004/09/22 13:38
开 0	#	H-0
AQ	A C	ő.
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
((("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or obcane boronhydrides (dalkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) thihydroxybenzene (sohated adj electrons) (suffurous adj acid) thihydroxybenzene (sokated adj electrons) (suffurous adj acid) and (((451/41.ccls. and polish\$3) and pad) or ((451/56.ccs. and polish\$3) and pad)) not (((451/41.ccls. and polish\$3) and pad)) not (((451/41.ccls. and polish\$3) and pad) and ((("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane borohydrides (dalkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (sokvated adj electrons) (suffurous adj acid) 1 and (((451/41.ccls. and polish\$3) and pad) or ((451/56.ccls. and polish\$3) and pad)) or ((451/60.ccls. and polish\$3) and pad)))	((451/41.ccts. and polish\$3) and pad) and (((73-hydroxy-4-pyrones") or (hydroxy adj) butyrolactones) or borane borohydrides (dalkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (solvated adj electrons) (sulfurous adj acid) trihydroxybenzene (solvated adj electrons) (sulfurous adj acid)) and (((451/41.ccls. and polish\$3) and pad) or ((451/66.ccls. and polish\$3) and pad) or ((451/60.ccls. and polish\$3) and pad)) or ((451/60.ccls. and polish\$3) and pad))	(("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane borohydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (sohvated adj electrons) (suffurous adj acid) and (((451/56.ccls, and polish\$3) and pad) or ((451/60. ccls, and polish\$3) and pad)
49	588	86
255	253	828

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525

S26

257

828

288	(("3-hydroxy-4-pyrones") or (hydroxy add) tutyrolactones) or borane borohydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (solvated adj electrons) (sulfurous adj acid)) and ((451/41.ccls. and polish\$3) and pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ő.	PFF OFF	2006/02/14 15:39
3038	oxidize\$4 and abrasive and polish\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	S.	DFF.	2004/09/22 14:22
=	oxidize\$2 and abrasive and polish\$4 and (reducing ad) agent) and ((liquid or aqueous) ad) carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT	A N	OFF.	2004/09/22 14:18
12	("4769046" "5489233" "552742" "5958794" "6001269" "601506" "6117783" "612632" "2002/0004360" "2002/0010332" "2002/0017630").PN.	USPAT	%	± ₀	2004/09/22 14:19
77604	tantalum	US-PGPUB; USPAT; EPO; JPO; DERWENT	S.	0FF	2004/09/22 14:22
2905	451/41.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	S.	OFF	2004/09/22 14:23
130	tantalum and 451/41.ccfs.	US-PGPUB; USPAT; EPO; JPO; DERWENT	S.	OFF	2004/09/22 14:23
895	(\$1-alumina or alpha-alumina or (alpha near alumina)) with abrasive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	ao R	9FF	2005/01/21 15:29
0	"451.clas"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/21 15:11

S29

230

S31

232

S33

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2005/01/21 15:12	2005/01/21 16:01	2005/01/21 15:30	2005/01/21 15:30	2005/01/21 15:31	2005/01/21 16:01	2005/01/21 16:01	2005/01/21 16:01	2005/01/24 09:38	2005/01/24 10:45	2005/01/24 10:48
0FF	H0	0FF	#0 #	0H	- OFF	9H	#0	#	0FF	0FF
OR	æ	80 R	8	æ	8	8 8	8	8	a R	OR
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
"451",clas.	S32 and S34	(silica or (fumed adj alumina)) with abrasive	(S32 or S36) and S34	S35 and (reducing adj agent)	S37 and (reducing adj agent)	S36 and S34	S40 and (reducing adj agent)	"6454822".pn.	"451".clas.	S43 and ((iridium adj oxide) or (tantalum same (oxidized, oxide, oxidizer))) and ((polishing adj pad or abrasive))
64929	99	6947	1138	11	27	1109	24	7	64929	195
234	235	836	237	8238	833	S40	241	242	243	844

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2005/01/24 09:58	2005/01/24 09:59	2005/01/24 10:08	2005/01/24 11:17	2005/01/24 10:15	2005/01/24 10:15	2005/01/24 10:15	2005/01/24 10:15	2005/01/24 10:16
FF 0	FF 0	H0	开0	H0	H 0	# #	H ₀	H0
æ	OR	A R	R	a a	a a	OR.	OR.	S.
US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	USPAT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCK; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
S43 and ((Iridium adj oxide) or (tantalum same (oxidized, oxide, oxidizet))) and ((polishing adj pad) or abrasive)	(US-20020182982-\$ or US-20030013387-\$ or US-20030023995-\$ or US-20040132385-\$).did. or (US-6454822-\$ or US-6709316-\$). did.	S45 and S46	(silicone adj oxide) with "Si"	silicone near4 metal	silicone near2 metal	silicone near1 metal	S43 and S51	S43 and S50
195	Φ	2	37	6851	2852	740	-	Ŋ
245	246	547	848	249	820	551	225	883

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2005/01/24 10:16	2005/01/24 10:17	2005/01/24 10:23	2005/01/24 10:24	2005/01/24 10:47	2005/01/24 10:46	2005/01/24 10:49	2005/01/24 10:49	2005/01/24 10:50	2005/01/24 11:17
FF0	开 0	100	0FF	H0	H0	丑	HO.	#6	₩
æ	æ	a R	8 S	80	S.	8 8	OR.	OR	OR
US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT				
S43 and S49	S54 not S51	S54 not S53	S47 and (Iridium adj oxide)	S43 and (iridium adj oxide)	"428".clas.	(substrate or wafer or semiconductor or semi-conductor) with (iridium adj oxide)	S43 and (iridium adj oxide)	((substrate or wafer or semiconductor or semi-conductor) with (iridium adj oxide)) and ((polishing adj pad) or abrasive)	(copper adj oxide) with "Cu"
11	10	9	0	2	212721	609	2	15	1388
854	\$55	928	252	828	828	98	S61	295	S63

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2005/01/24 11:17	2005/01/24 13:23	2005/01/24 13:23	2005/01/24 13:24	2005/01/24 13:24	2005/01/24 14:09	2005/01/24 14:09	2005/01/24 14:11	2005/07/12 10:33	2005/07/12 10:33	2005/07/12 10:33
#6	9H	刊0	# Ho	# #	₽ H	±0	HO.	Ð.	OFF	0 斤
a S	OR	9 8	OR	OR.	A R	OR	æ	80	R	OR
US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
S63 and S43	(Iridium adj oxide) and (polish polishing CMP ("chemical mechanical polishing"))	S65 and (reducing adj agent)	(iridium adj oxide) and (CMP ("chemical mechanical polishing"))	(retium adj oxide) and (CMP or ("chemical mechanical polishing"))	(indium adj oxide) same (CMP or ("chemical mechanical polishing"))	"4717581".pn.	"4679572".pn.	451/41.ccks. and polish\$3	451/56.ccls. and polish\$3	451/60.ccls. and polish\$3
80	999	4	569	695	\$	7	7	2567	220	427
564	S9S	998	298	898	698	870	S71	225	S73	574

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2005/07/12 10:43	2005/07/12 10:55	2005/07/12 10:43	2005/07/12 10:44	2005/07/12 10:44	2005/07/12 10:56	2005/07/12 11:00	2005/07/12 11:05	2005/07/12 11:05
FF0	开0	7F0	90FF	0FF	升0	H0	9 F	H0
8	8 8	Se .	8	g g	g g	g g	8	NO.
US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
(S72 S73 S74) and ("pH" near2 (buffering buffer buffer\$4))	(S72 S73 S74) and (surfactant)	(ammonium adj hydroxide) same ("pt" near2 (buffering buffer buffer\$4))	(ammonium adj hydroxide) with ("ph" near2 (buffering buffer buffer\$4))	(ammonium adj hydroxide) near4 ("pH" near2 (buffering buffer buffer\$4))	(\$72 \$73 \$74) and ((advantages advantageous advantag\$5) with surfactant)	("451".clas.) and ((advantages advantageous advantag\$5) with surfactant)	("451".clas.) and ((desired improve improved improvement) with surfactant)	"5783489".pn.
08	266	1183	366	105	8	'n	6	2
875	876	272	828	579	088	281	285	283

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4 16:29	4 15:44	4 15:45
2006/02/14 16:29	2006/02/14 15:44	2006/02/14 15:45
2	7	2
940	Но	1 90
ж о	80	A S
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
(polishing adj (pad pads)) and (CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and ((reducing adj agent) with (hydroxylamine and (("3-hydroxy-4-pyrones") or (hydroxy adj 1 butyrolactones) or borner or bornborty poranes or (dialkylamine adj boranes) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$\frac{1}{2}\$ or hydrogen or hydroquinone\$\frac{1}{2}\$ or hydrogen or hydroquinone\$\frac{1}{2}\$ or hydrogen or kydroquinone\$\frac{1}{2}\$ or hydrogen or kydroquinous adj acid)))	(polishing adj (pad pads)) and (CMP or "chemical mechanical polishing" or "chemical mechanical polishing" or "chemical mechanical palnarization") and ((reducing adj agent) with (frydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or (hydroxy adj1 butyrolactones) or (hydroxy adj1 butyrolactones) or or (dalkylamine adj boranes) or formaldehyde or (formic adj acld) or hydrogen or hydroquinone\$\frac{1}{2}\$ or hydrogen or hydroquinone\$\frac{1}{2}\$ or hydrogen or hydroquinone\$\frac{1}{2}\$ or hydrogen or kydroquinone\$\frac{1}{2}\$ or hydrogen or kydroquinous adj electrons) or (suffurous adj acid))))	((reducing adj agent) with (hydroxylamine with ("C3-hydroxy-4-pyrones") or (hydroxy adj butyrolactones) or borane or borohydrides or (dlalkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or hydrogen or hydroquinone\$3 or thlypophosphorous adj acid) or thlhydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))
m	m	241
884	\$88	985

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2006/02/14 15:45	2006/02/14 16:56	2006/02/14 15:49
H 0	# 6	# #
Я	Ř	ж
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
(polishing adj (pad pads)) and ((reducing adj agent) with (indroxyamine with ((73-hydroxy-4 pyrones-) or (hydroxy adj butyrolactones) or (hydroxy adj butyrolactones) or (alaikyamine adj boranes-3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinones-3 or (hypophosphorous adj acid) or hydroxybenzene or (sofvated adj electrons) or (suffurous adj acid)))	(CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and (ireducing adjagent) with (hydroxylamine and ("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or (hydroxy adj1 butyrolactones) or (alaikylamine adj borane or borohydrides or (dalikylamine adj borane\$3) or formaldehyde or (formica) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or thinydroxybenzene or (sofvated adjectons) or (suffurous adjaged))))	(semiconductor wafer polish planarize substrate copper) and (ircalucing adi agent) with (hydroxylamine and ([73-hydroxy-4-pyrones") or (hydroxy adij butyrolactones) or (hydroxy adij butyrolactones) or (hydroxy adij butyrolactones) or (hydroxy adij butyrolactones) or (hydroxylamine adi boranes) or formaldehyde or (formic adi acid) or hydrogen or hydroquinones) or hydrogen or hydroquinones) or trihydroxylenraene or (solvated adi electrons) or (sulfurous adi acid)))
m	w	185
287	88	688

2006/02/14 15:49	2006/02/14 15:49	2006/02/14 15:49	2006/02/14 15:56
H 0	H 0	± 0	
A.	ಜ	A S	A .
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; PO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
(wafer polish planarize substrate copper) and ((reducing ad) agent) with (hydroxylamine and (("3-hydroxy-4-pyrones") or (hydroxy adj.1 butyrolactones) or borane or borohydrides or (dialkylamine adj boranes) or formaldehyde or (formic adj acd) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adj acid))))	(semiconductor polish planarize substrate copper) and ((reducting ad agent) with (hydroxylamine and (("3-hydroxy-4-pyrones") or (hydroxy adj 1 butyrolactones) or borane or borohydrides or (dulkylamine adj boranes) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or hydroxybenzene or (solvated adj electrons) or (suffurous adj acid)))	(semiconductor planarize substrate copper) and ((reducing ad agent) with (hydroxydamine and (("3-hydroxy-4-pyrones") or (hydroxy adj 1 butyrolactones) or borane or borohydrides or (balkylamine adj boranes\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or hydroxybenzene or (solvated adj electrons) or (sulfurous adj acid)) add)),	(semiconductor substrate copper) and ((reducing adj agent) with (hydroxylamine and ("G-hydroxy-4-pyrones") or ("G-hydroxy adj) butyrolactones) or borane or borohydrides or (dialkylamine adj borane\$3) or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or trihydroxybenzene or (sohvated adj electrons) or (suffurous adj acid))))
176	185	185	185
065	165	285	293

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2006/02/14 15:50	2006/02/14 15:50	2006/02/14 16:11	2006/02/14 16:11
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US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
(semiconductor copper) and ((reducing adj agent) with (hydroxydamine and (('3-hydroxy-a-pyrones") or (hydroxy adj1 butyrolactones) or borane or borohydrides or (dalkydamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or fylpophosphorous adj acid) or hydroyenzene or (solvated adj electrons) or (suffrrous adj acid)))	(semiconductor substrate) and ((reducing adj agent) with (indroxylamine and ((73-hydroxy-4-pyrones") or (hydroxy adj 1 butyrolactones) or borane or borohydrides or (lalkylamine adj boranes) or formaldehyde or (formic adj acid) or hydrogen or hydroquinones 30 or hydrogen or hydroquinones 30 or (hypophosphorous adj acid) or hydroxybenzene or (sohvated adj electrons) or (suffurous adj acid)))	(semiconductor semiconductors) and ((reducing adj agent) with hydroxyamine and ((13-hydroxy-4-pyrones*) or (hydroxy adj butyrolactones) or borane or borohydrides or (dialkyamine adj borane\$3) or formaldehyde or (formic adj add) or hydrogen or hydroquinone\$3 or (hypophosphorous adj add) or thydroxybenzene or (sohated adj electrons) or (sulfurous adj add)))	(("451".clas.) or ("428".clas.) or ("51".clas.)) and ((reducing adjagent) with (hydroxylamine and (("3-hydroxy-4-pyrones") or (hydroxy adj butyrolactones) or borane or borohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formadehyde or (formadehyde) or hydrogen or hydroguinone\$3 or (hypophosphorous adjacid) or trihydroxybenzene or (sohated adjectrons) or (suffurous adjacid)) acid)).
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((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical polishing" or "chemical mechanical planarization") and ((reducing adj agent) with (("3-hydroxy-4-pyrones") or (hydroxy adj 1 butyolactones) or borane or borohydrides or (formic adj acid) or formaldehyde or (formic adj acid) or hydrogen or hydroquinones3 or (hypophosphorous adj acid) or trihydroxybenzene or (sohvated adj electrons) or (sulfurous adj acid)))	((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical polishing" or "chemical mechanical polishing" or "chemical furry composition solution) and (slurry composition solution) and ((reducing adj agent) with (("3-hydroxy 4-pyrones") or (hydroxy adj1 butynolactones) or (hydroxy adj1 butynolactones) or (dalkylamine adj borane\$3) or formaldehyde or (formic adj acid) or fyrdrogen or hydroquinone\$3 or fyrdrogen or hydroquinone\$3 or hydrogen or sydroquinone\$3 or hydrogen or kydroquinone\$3 or hydrogen or kydroquinone\$3 or hydrogen or kydroquinone\$3 or hydrogen or kydroquinone\$3 or kydrogen or kydroquinone\$3 or kydrogen or kydroquinone\$3 or kydrogen or kydroquinone\$3 or kydrogen or kydrogen or kydroquinone\$3 or kydrogen o	((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical palnarization")) and (slurry composition) and (slurry agent) with ("C3-hydroxy-4-pyrones") or ("C3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane or borohydrides or (hydroxy adj1 butyrolactones) or or hydrogen or hydroquinones;3 or or hydrogen or hydroquinones;3 or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid)))
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((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical polishing" or "chemical mechanical planarization")) and ((reducing adj agent) with (("3-hydroxy-4-pyrones") or (hydroxy adj butyrolactones) or borane or borohydrides or character (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydroquinone\$3 or hydroquinone\$4 or hydroquinone\$4] or thihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))	(CMP or "chemical mechanical polishing" or "chemical mechanical polishing" or "chemical mechanical phanartation") and ((reducing adjagent) with ((hydroxylamine glucose sulfothionate (potasslum adjoldeh)) with (("3-hydroxy-4-pyrones") or (hydroxy adj 1 butyrolatchores) or borane or borohydrides or chydrosen or borohydrides or formaldehyde or (formic adjacid) or hydrogen or hydroquinone\$3 or (hypophosphorous adjacid) or thydroxybenzene or (solvated adjelectrons) or (sulfurous adjacid)))	(CMP or "chemical mechanical polishing" or "chemical mechanical phanarization") and (freducing adjagens) with (hydroxylamine with (("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or (hydroxy adj1 butyrolactones) or (dialikylamine adj boranes) or formadehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or tilhydroxybenzene or (solvated adjelectrons) or (suffurous adjacid))))
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(CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and ((reducing adjagent) with ((glucose sulfothionate (potassium adjihodide)) with (("3-hydroxy-dyrones") or (hydroxy adji butyrolactones) or borane or borohydrides or (dalkyamine adj borane adj acida) or hydroquinone\$3 or formaldehyde or (formic adjadid) or hydrogen or hydroquinone\$3 or thydrosphorous adj acid) or trihydroxybenzene or (solvated adjelectrons) or (sulfurous adj	((polishing adj (pad pads)) or planarize planarization slurry) and ((reducing adj agent) with ((glucose sulfothlonate (potasslum adj loidde)) with (("3-hydroxy-4-pyrones") or (hydroxy adj 1 butyrolacitones) or borane or borohydrides or (dlakylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or frhypophosphosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))	((polishing adj (pad pads)) or planarize planarization) and ((reducing adj agent) with ((glucose suifothionate (potassium adj loidide)) with (("3-hydroxy-4-pyrones") or (hydroxy adj b tutyrolactones) or borane or borohydrides or (dalkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid) acid))))
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(CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and planarization") and planarization") and planarization") and planarization and planarizatio	(CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and (hydroxylamine with (("3-hydroxy-4-pyrones") or (hydroxy adj 1 butyrolactones) or borane or borohydrides or (dialkylamine adj borane adj adj or hydronen or hydronin adj adj or hydronen or hydroninnes 3 or hydr	(hypophosphorous adj acid) or trihydovzybenzene or (sokvated adj electrons) or (suffurous adj acid) or trihydroxybenzene or (sokvated adj electrons) or (suffurous adj acid) or (thydroya adj peroxide))) (CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and (hydroxyamine with (("3-hydroxyamine with ("3-hydroxyamine with ("3-hydroxyamine adj brotrones) or (hydroxyamine adj boranes) or dialkiylamine adj boranes) or dialkiylamine adj boranes) or formaldehyde or (formic adj acid) or (hydrogen adj peroxide) or (hydrogen adj peroxide) or hydroquinones3 or hydr	(Inypopnosphotous adjacta) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adjactd))) S107 not S109
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(CMP or "chemical mechanical polishing" or "chemical mechanical phararization") and diplanarization") and hydroxylamine with (("3-hydroxy-4-pyrones") or (hydroxylamine with borner or borohydrides or (hydroxy adj 1 butyrolactones) or (hydroxyamine adj boranes) or borner or borohydrides or (dalkylamine adj boranes) or formaldehyde or (formic adj acid) or hydroquinone\$3 or (hypophosphorous adj acid) or hydroquinone\$3 or thihydroxybenzene or (sohvated adj electrons) or (sulfurous adj acid)))	(complexing adj agent) with (chelating adj agent)	10/753138.app.	("20020039839" "20020090820" " 20020102923" "20020111027" "2 0030013887" "20030119119" "54 89233" "5527423" "5691219" "62 58794" "6117783" "6139763" "62 74063" "6313039" "64	09/755717.app.
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